



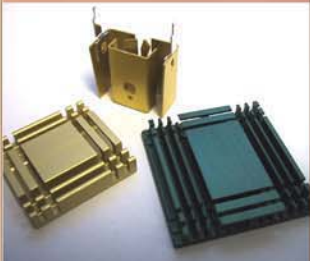
**Stamped Heat Sinks
For Transistor Packages**

- TO-126
- TO-127
- TO-202
- TO-218
- TO-220
- TO-247
- TO-3



FECOM has been established to manufacture and market heat sinks and other types of thermal management products.

FECOM's operation is also geared to provide our customers with custom parts and complete design services in order to meet their special needs for thermal treatment. We can perform minor modifications on our standard parts to achieve cost savings for our customers.



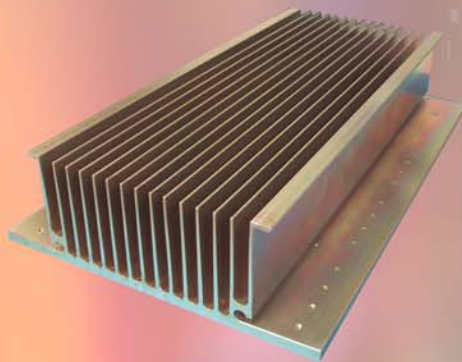
Finish Types

- Black Anodize
- Clear Anodize
- Clear Chromate
- Gold Chromate
- Tin Plated
- Pre-Tinned Copper
- Electronic Coating
- Red Anodize
- Blue Anodize

OPTIONS & ACCESSORIES

Clips, Hardware & Solderable tabs available for mounting and assembling the semiconductors to heat sinks

Interface material can be applied to heat sinks (silicon pad, thermal adhesive, double sided tape).



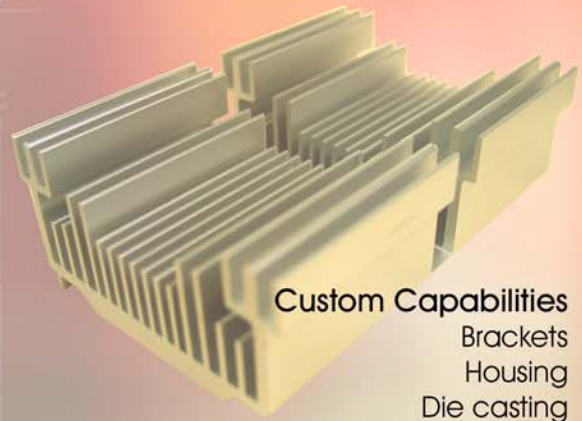
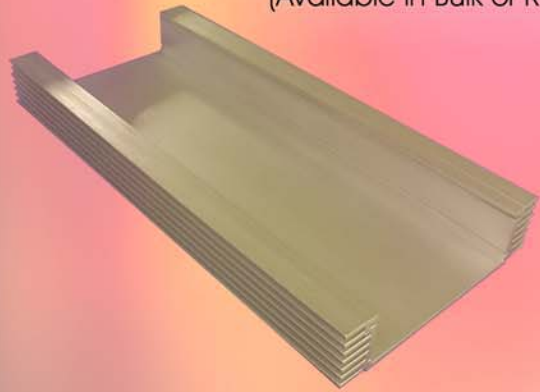
WWW.FECOMCORP.COM

FECOM CORPORATION

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Wide Product Selection

- 'Stamped Heat Sinks'
- 'Extruded Heat Sinks'
- 'Microprocessor Heat Sinks'
- 'Standard Extrusion Profiles'
- 'Assembled Fin'
- 'Folded Fin'
- 'BGA and PGA Heat Sinks'
- 'Surface Mount Heat Sinks'
- (Available in Bulk or Reels)



Custom Capabilities

- Brackets
- Housing
- Die casting
- Front Panel, chassis, and covers
- Custom CNC machined heat sinks
(max width: 400mm / max height: 40mm)

Custom extrusions can be made based on customer's print

Wide variety of extrusion profiles available that can be machined to meet special needs